



Product Change Notification

Change Notification #: 115678 - 00
Change Title: Intel® AnyWAN™ GRX750 SoC - CE2732,
Intel® AnyWAN™ GRX750 SoC - CE2733,
Intel® Puma™ 7 SoC CE2703,
Intel® Puma™ 7 SoC CE2712,
Intel® Puma™ 7 SoC CE2712M,
Intel® Puma™ 7 SoC CE2752,
Intel® Puma™ 7 SoC CE2752M,
Intel® Puma™ 7 SoC CE2753,
**PCN 115678-00, Manufacturing Site, Label,
Transfer of assembly/test for PUMA7 from
Malaysia to Vietnam**

Date of Publication: July 19, 2017

Key Characteristics of the Change:

Manufacturing Site

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	October 02, 2017
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Description of Change to the Customer:

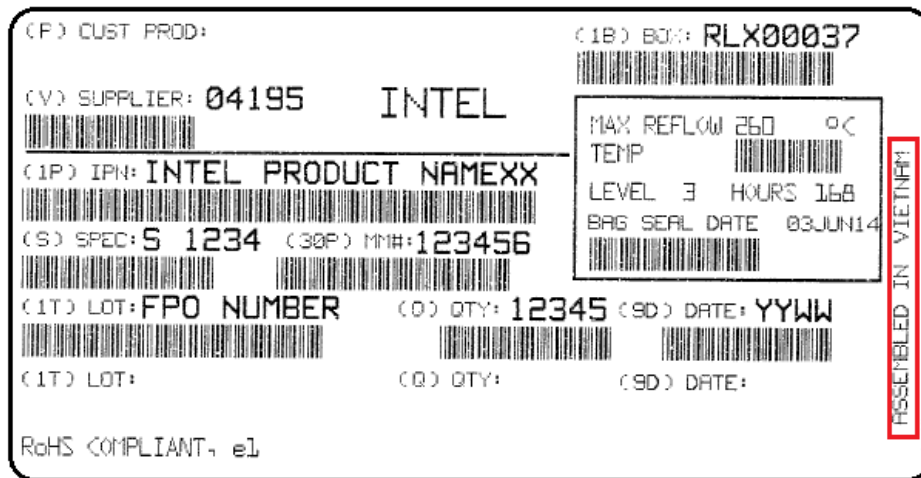
In order to ensure a continuous supply of the Intel® AnyWAN™, and Intel® Puma™ 7 products listed in the "Products Affected" Table below, Intel will now manufacture these products using another Intel qualified assembly site. The new site is located in Vietnam. The new manufacturing site has been certified equivalent (form, fit, function, and reliability) for the affected products and technologies of this change.

Intel will transfer the assembly and test operation for the Puma7 product family from our production site in Malaysia to our site in Vietnam to make sure we have sufficient capacity to meet customer demand from Q4 onwards.

There will be a cutover period where customers may receive material from Malaysia and Vietnam until the available stock is depleted. This may be different for each individual part number depending on stock and demand.

There will be no mixed shipment. One shipment will only contain material from one site. Samples will be available from October onwards on request.

Due to this change, the "ASSEMBLED IN Country" on the box label will now include Vietnam. See label example below – This label is a representation for example purposes only. The actual label will reflect correct product data.



Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers for this change. Customers may see products from all assembly sites. Customers may want to notify their receiving department of the additional country listed on the label. Customers should update their import processes/data to make sure that they are able to receive shipments of material from Vietnam. Customers may contact their Intel Field Sales Representative or the contacts listed on the last page of this Product Change Notification appropriate to your geo with questions.

Marking and Spec codes will stay the same. Only the label will show the new country of origin.

Customers should update their import processes/data to make sure that they are able to receive shipments of material from Vietnam.

Fabrication (Fab), sort, and assembly test facilities follow a Copy Exactly! (CE!) philosophy. Copy Exactly! enables delivery of product from multiple production sites, which operate as a virtual factory that performs consistently and independent of the manufacturing source site. Additional benefits include faster production ramps that improve product availability and improved consistency to quality performance.

Learn more about CE! At <http://www.intel.com/content/www/us/en/quality/exact-copy.html> web site.

Products Affected / Intel Ordering Codes:

Marketing Name	Stepping	Product Code	S-Spec	MM#
Intel® Puma™ 7 SoC CE2752 DOCSIS3.1 Services & All-IP Video Gateway	B0	FHCE2752	S R31A	952322
Intel® Puma™ 7 SoC CE2752M DOCSIS3.1 Services & All-IP Video Gateway with MOCA	B0	FHCE2752M	S R31B	952331
Intel® Puma™ 7 SoC CE2703 DOCSIS3.1 (5Gbps) Data Modem/eMTA	B0	FHCE2703	S R31E	952346
Intel® Puma™ 7 SoC CE2712 DOCSIS3.1 Entry Level Networking GW	B0	FHCE2712	S R31F	952347
Intel® Puma™ 7 SoC CE2712M DOCSIS3.1 Entry Level Networking GW with MOCA	B0	FHCE2712M	S R31G	952348
Intel® Puma™ 7 SoC CE2753 Enterprise Access Point with DOCSIS3.1 Backhaul	B0	FHCE2753	S R31H	952354
Intel® AnyWAN™ GRX750 SoC - CE2733 Enterprise Access Point	B0	FHCE2733	S R35Y	954095
Intel® AnyWAN™ GRX750 SoC - CE2732	B0	FHCE2732	S R3AM	955500

PCN Revision History:

Date of Revision:

July 19, 2017

Revision Number:

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Reason:

Originally Published PCN



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The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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